

S/N 09/829,749

Docket: FIS920010045US1

IN THE CLAIMS:**Please revise the claims as follows:**

1. (Previously presented) An electronic circuit wiring interconnect package test and repair apparatus, comprising:

at least one wiring analyzer to locate shorts between conductors, said conductors being on a surface of or embedded in a carrier substrate, said conductors being intended to interconnect components to be mounted on said carrier substrate to form a circuit, said carrier substrate being devoid of all said components;

a current source to provide current sufficient to remove said shorts; and

a cluster probe, comprising a plurality of probes, to contact said conductors in a manner controlled by said wiring analyzer.

2. (Original Claim) The test and repair apparatus of claim 1, wherein said at least one wiring analyzer comprises at least one relay wiring analyzer and at least one solid state wiring analyzer, thereby providing at least two different testing speeds.

3. (Previously presented) The test and repair apparatus of claim 1, further comprising a controller for automatic positioning of said cluster probe.

4. (Cancel)

5. (Original Claim) The test and repair apparatus of claim 1, further comprising a controller having voltage stress test capability.

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upon
Appeal
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